Abstract

A lid for use with a plate-shaped base to seal an electronic device such as a SAW device includes a top portion, a wall structure extending from the top portion, and a lip connected to the lower end of the wall structure. The lip extends

outwards from an outer surface of the wall structure by 10 - 500 µm and has solder on an inner surface thereof. The lid can be soldered to a plate-shaped base to form a package. The lid can be conveniently formed by performing drawing of a metal strip coated with solder to define a recessed shape, and then severing a flange of the recessed shape to define the lip.